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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

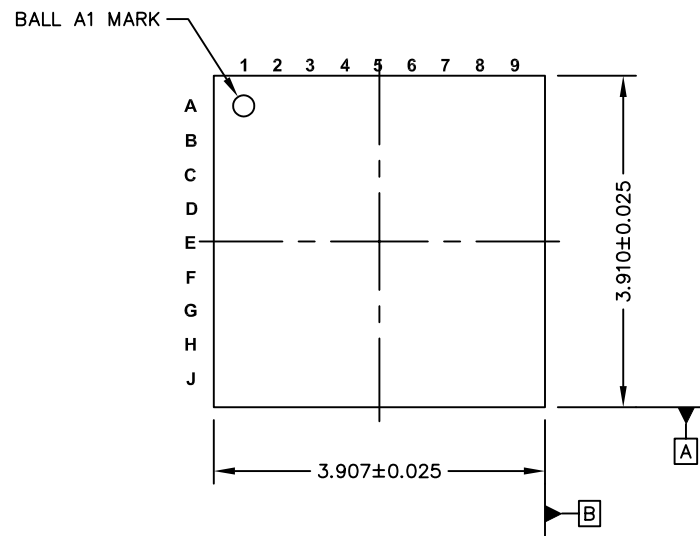
Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

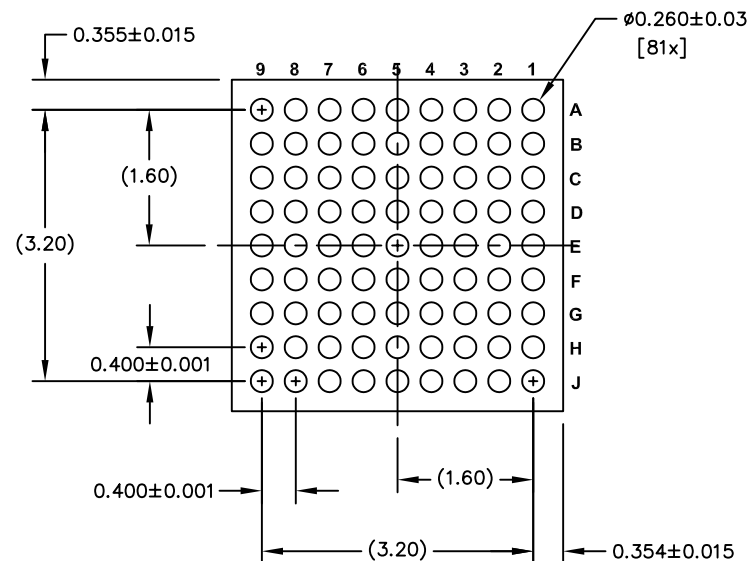
Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

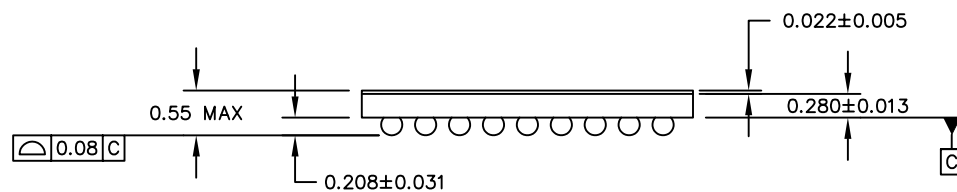
TOP VIEW



BOTTOM VIEW




SIDE VIEW



NOTES:

1. ALL DIMENSION ARE IN MM
2. PACKAGE WEIGHT: See Cypress Package Material Declaration Datasheet (PMDD) posted on the Cypress Web
3. JEDEC – Publication 95; Design Guide 4.18

 CYPRESS Company Confidential	
TITLE PACKAGE OUTLINE, ASTORIA WLCSP 3.91X3.91X0.55 MM FN81B	
SPEC NO. 001-45618	REV *D
SCALE	SHEET 1 OF 2

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PACKAGE CODE(S)

1	2	3	4	5	6																									
A	<table border="1"><thead><tr><th>Rev</th><th>ECN No.</th><th>Orig. of change</th><th>Description of Change</th></tr></thead><tbody><tr><td>**</td><td>2323866</td><td>MLA</td><td>NEW SPEC</td></tr><tr><td>*A</td><td>2561080</td><td>MLA</td><td>CHANGE BSL DIMENSION FROM 0.040 TO 0.022</td></tr><tr><td>*B</td><td>2819358</td><td>TZWTMP3</td><td>CHANGE TEMPLATE, CHANGE TITLE FROM ASTORIA WLCSP PACKAGE OUTLINE TO PACKAGE OUTLINE, ASTORIA WLCSP 3.91X3.91X0.55 MM FN81B</td></tr><tr><td>*C</td><td>3530671</td><td>MLA</td><td>REVISE STATEMENT REGARDING PACKAGE WEIGHT.</td></tr><tr><td>*D</td><td>4683551</td><td>ROWI</td><td>SUNSET REVIEW, NO CHANGE.</td></tr></tbody></table>					Rev	ECN No.	Orig. of change	Description of Change	**	2323866	MLA	NEW SPEC	*A	2561080	MLA	CHANGE BSL DIMENSION FROM 0.040 TO 0.022	*B	2819358	TZWTMP3	CHANGE TEMPLATE, CHANGE TITLE FROM ASTORIA WLCSP PACKAGE OUTLINE TO PACKAGE OUTLINE, ASTORIA WLCSP 3.91X3.91X0.55 MM FN81B	*C	3530671	MLA	REVISE STATEMENT REGARDING PACKAGE WEIGHT.	*D	4683551	ROWI	SUNSET REVIEW, NO CHANGE.	A
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SCALE		SHEET	2 OF 2



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SPEC NO.	001-45618	REV	*D
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